

DESCRIPTION

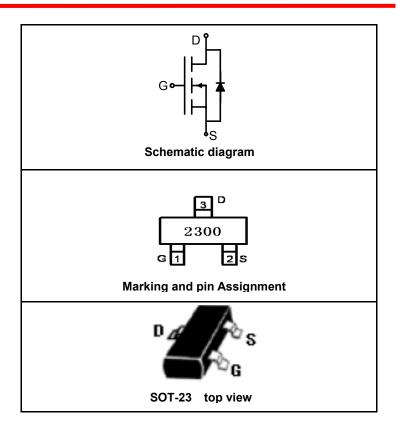
The FNK 2300 uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

GENERAL FEATURES

- V_{DS} = 20V, I_D =3.5A $R_{DS(ON)}$ < 43mΩ @ V_{GS} =2.5V $R_{DS(ON)}$ < 31mΩ @ V_{GS} =4.5V
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

- Battery protection
- Load switch
- Power management



PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2300	FNK 2300	SOT-23	Ø180mm	8 mm	3000 units

ABSOLUTE MAXIMUM RATINGS(TA=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	20	V
Gate-Source Voltage	Vgs	±10	V
Dunin Comment Continuous & Comment Dulead (Nate 1)	I _D	3.5	А
Drain Current-Continuous@ Current-Pulsed (Note 1)	I _{DM}	16	А
Maximum Power Dissipation	P _D	1.2	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$ C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	140	°C/W
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ELECTRICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20			V



FNK2302

Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V,V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V,V _{DS} =0V			±100	nA
ON CHARACTERISTICS (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.4	0.7	1.0	V
Drain-Source On-State Resistance	В	V _{GS} =2.5V, I _D =4A		28	43	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =4.5A		25	31	mΩ
Forward Transconductance	g FS	V _{DS} =10V,I _D =4.5A		5		S
DYNAMIC CHARACTERISTICS (Note4)						
Input Capacitance	C _{lss}			500		PF
Output Capacitance	C _{oss}	V_{DS} =10V, V_{GS} =0V, F=1.0MHz		250		PF
Reverse Transfer Capacitance	C _{rss}			90		PF
SWITCHING CHARACTERISTICS (Note 4)					
Turn-on Delay Time	t _{d(on)}			7		nS
Turn-on Rise Time	t _r	$V_{DD}=10V, R_{L}=2.8 \Omega$		55		nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =4.5 V , R_{GEN} =6 Ω , I_D =3.6 A ,		16		nS
Turn-Off Fall Time	t _f			10		nS
Total Gate Charge	Qg			10		nC
Gate-Source Charge	Q_{gs}	V _{DS} =10V,I _D =4.2A,V _{GS} =4.5V		2.3		nC
Gate-Drain Charge	Q_{gd}			2.9		nC
DRAIN-SOURCE DIODE CHARACTERIST	ics	•	•	•	•	•
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =1.3A			1.2	V

NOTES:

- Repetitive Rating: Pulse width limited by maximum junction temperature.
 Surface Mounted on FR4 Board, t ≤ 10 sec.
 Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
 Guaranteed by design, not subject to production testing.



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

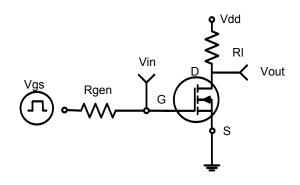


Figure 1:Switching Test Circuit

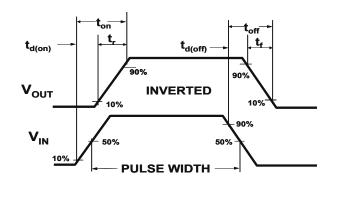


Figure 2:Switching Waveforms

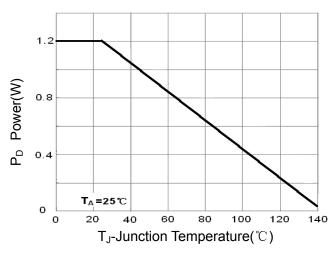


Figure 3 Power Dissipation

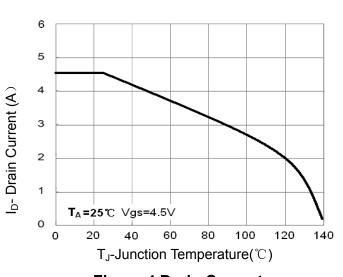


Figure 4 Drain Current

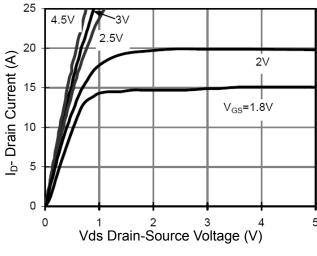


Figure 5 Output CHARACTERISTICS

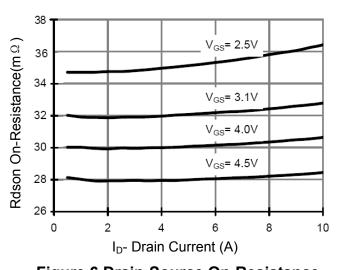


Figure 6 Drain-Source On-Resistance



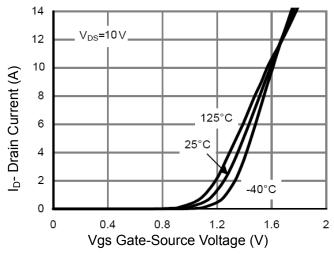


Figure 7 Transfer Characteristics

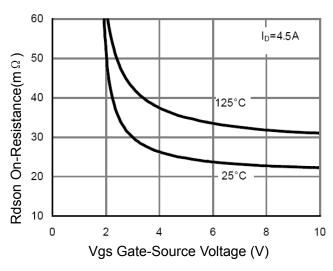


Figure 9 Rdson vs Vgs

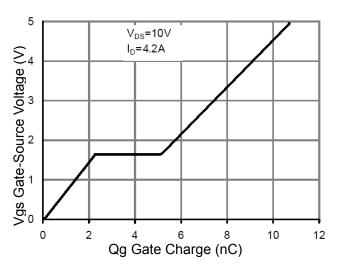


Figure 11 Gate Charge

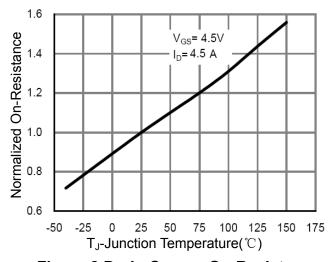


Figure 8 Drain-Source On-Resistance

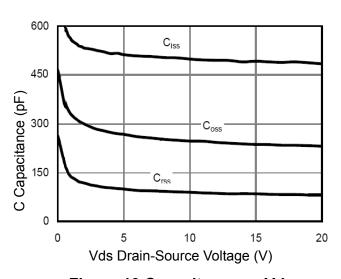


Figure 10 Capacitance vs Vds

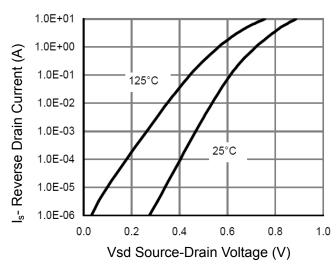


Figure 12 Source- Drain Diode Forward



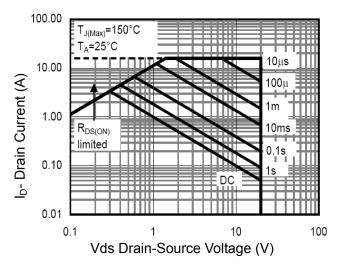


Figure 13 Safe Operation Area

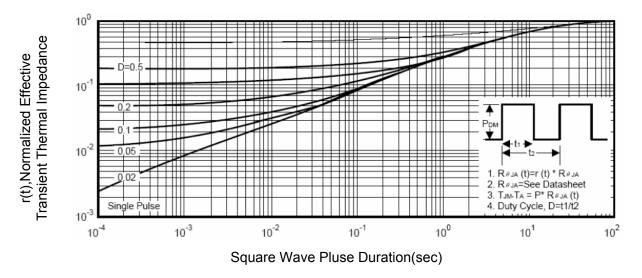


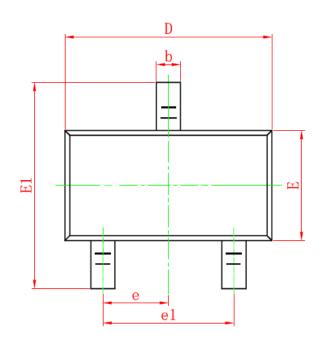
Figure 14 Normalized Maximum Transient Thermal Impedance

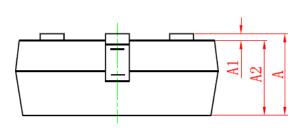
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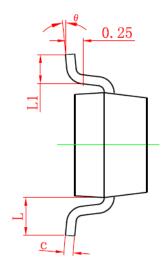


SOT-23 PACKAGE INFORMATION

Dimensions in Millimeters (UNIT:mm)







Symbol	Dimensions in Millimeters			
Symbol	MIN.	MAX.		
Α	0.900	1.150		
A1	0.000	0.100		
A2	0.900	1.050		
b	0.300	0.500		
С	0.080	0.150		
D	2.800	3.000		
E	1.200	1.400		
E1	2.250	2.550		
е	0.950TYP			
e1	1.800 2.000			
L	0.550REF			
L1	0.300 0.500			
θ	0°	8°		

NOTES

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



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